

ABSTRACT

A bonding apparatus includes a bonding tool, first and second imaging units, a calculation part, and a drive control part. The first and second imaging units each include an optical system and an imaging element arranged to satisfy a Scheimpflug condition such that a plane parallel to a stage surface becomes a focal plane. The calculation part calculates three-dimensional coordinates of a target point to which a bonding wire is to be supplied next among bonding points, based on a first picture which is a picture of the target point captured in a first image outputted by the first imaging unit, and a second picture which is a picture of the target point captured in a second image outputted by the second imaging unit. The drive control part causes the bonding tool to approach the target point based on the three-dimensional coordinates of the target point.

This bonding device comprises: a bonding tool that supplies a bonding wire to a bonding point of a substrate placed on a stage; first and second imaging units in which optical systems and imaging elements thereof are disposed so as to satisfy a Scheimpflug condition so that a flat surface parallel to a stage surface of the stage becomes a focal surface; a calculation part that calculates three-dimensional coordinates of a target point of the bonding points on the basis of a first picture being an image of the target point which is reflected in a first image outputted from the first imaging unit and at which the next bonding wire is to be supplied, and a second picture which is an image of the target point reflected in a second image outputted from the second imaging unit; and a drive control part that causes the bonding tool to approach the target point on the basis of the three-dimensional coordinates of the target point calculated by the calculation part.

Representative drawing: FIG. 1